

AN-1469 PHYTER Design & Layout Guide

ABSTRACT

This application report describes PHYTER™ design and layout guidelines.

Contents

1	Introduction	3
2	MDI (TP/CAT-V) Connections	4
	2.1 PCB Layout Considerations	5
	2.2 Calculating Impedance	6
	2.3 RJ-45 Connections	6
	2.4 MDI EMI Recommendations	7
3	Fiber Optic Implementations	7
4	Power Supply Filtering	7
	4.1 Power Feedback Supply	8
5	MAC Interface (MII/RMII)	8
	5.1 Termination Requirement	8
	5.2 Recommended Maximum Trace Length	8
6	Clock Requirements	9
	6.1 External Oscillator Clock Source	9
	6.2 Crystal Clock Source	9
7	LED and non-LED Strap Pins	10
8	PCB Layer Stacking	11
9	Unused Pins/Reserved Pins	12
10	Component Selection	12
	10.1 Oscillator or Crystal	12
	10.2 Magnetics	13
11	Reset Operation	14
	11.1 Hardware Reset	14
	11.2 Software Reset	14
12	Other Applicable Documents	15

List of Figures

1	Typical Application	4
2	10/100 Mb/s Twisted Pair Interface.....	4
3	Differential Signal Pair - Stubs	5
4	Differential Signal Pair-Plane Crossing	5
5	Microstrip Impedance - Single-Ended	6
6	Stripline Impedance - Single-Ended	6
7	Microstrip Impedance - Differential	6
8	Stripline Impedance - Differential	6
9	Vdd Bypass Layout	7
10	Power Feedback Connection.....	8
11	Oscillator Circuit.....	9

PHYTER is a trademark of Texas Instruments.
All other trademarks are the property of their respective owners.

12	Crystal Oscillator Circuit	10
13	AN Strapping and LED Loading Example	10
14	PCB Stripline Layer Stacking	11
15	Alternative PCB Stripline Layer Stacking.....	12

List of Tables

1	25 MHz Crystal Oscillator Requirements.....	13
2	25 MHz Crystal Requirements	13
3	Recommended Crystal Oscillators	13
4	Magnetics Requirements	14
5	Recommended Magnetics.....	14

1 Introduction

The PHYTER family of products are robust, full featured, low power, 10/100 Physical Layer devices. With cable length performance far exceeding IEEE specifications and features that provide lower cost solutions, for both 10BASE-T and 100BASE-TX Ethernet protocols, the devices ensure compatibility and interoperability with other standards based Ethernet products in these applications:

- High End Peripheral Devices
- Industrial Controls
- Factory Automation
- General Embedded Applications

Use of this application report, in conjunction with the product datasheets, and reference designs, will help ensure issue-free system products.

Topics covered include:

- MDI (Twisted Pair/CAT-V) Connections
- Power Supply Decoupling
- MAC Interface
- Clock Connections
- LED Connections
- Configuration (Strap) Connections
- Unused/Reserved Pins
- PCB Layers (stack-up)
- Component Selection/Recommendations

Product Applicability:

DP83640	DP83849C	DP83848C
DP83630	DP83849I	DP83848I
DP83620	DP83849ID	DP83848YB
	DP83849IF	DP83848VYB
		DP83848M
		DP83848T
		DP83848H
		DP83848J
		DP83848K
		DP83848Q-Q1

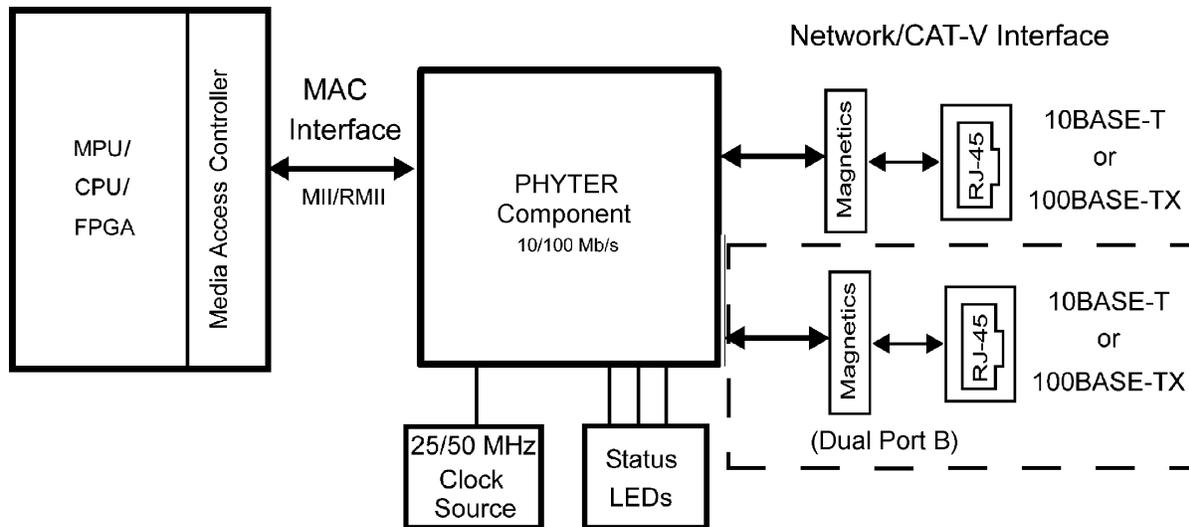


Figure 1. Typical Application

2 MDI (TP/CAT-V) Connections

The network or Medium Dependent Interface (MDI) connection is via the transmit (TD+ & TD-) and receive (RD+ & RD-) differential pair pins. These connect to a termination network, then to 1:1 magnetics (transformer) and an RJ-45. For space savings the magnetics and RJ-45 may be a single integrated component. A standard CAT-V Ethernet cable is then used to connect to the rest of the network. Figure 2 shows the recommended 10/100 Mb/s twisted pair interface circuit. PHYTER family termination and center tap connections are different from previous Ethernet devices.

In certain applications, an alternate method of connecting the PHYTER component to another device may be desirable. Specifically, designs for applications where a backplane is the choice of media between devices. In these applications DC isolation must be maintained, while providing an AC signal coupling path. This can be accomplished using capacitors for the connection instead of the magnetics. Specifics of this method of connection are provided in the AN-1519 DP83848 PHYTER® Transformerless Ethernet Operation Application Report (SNLA088).

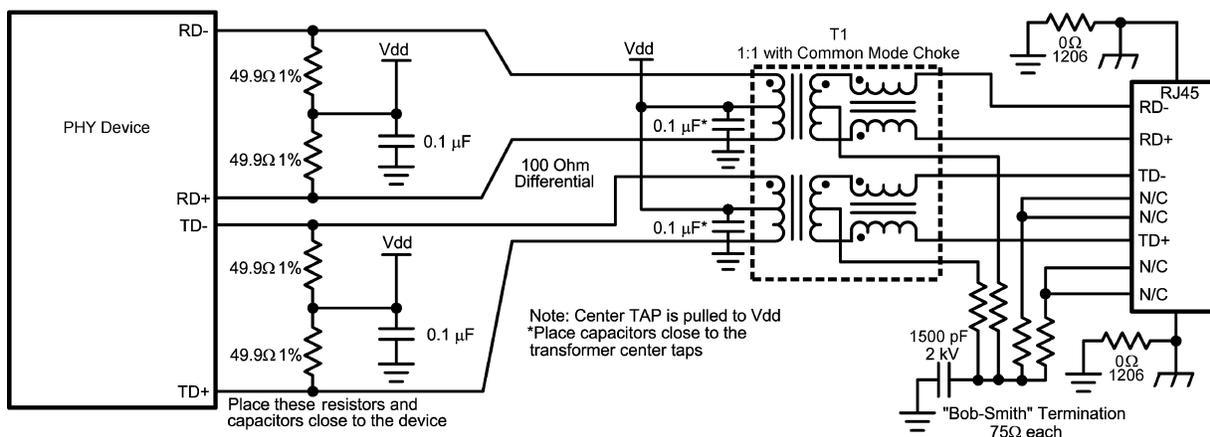


Figure 2. 10/100 Mb/s Twisted Pair Interface

2.1 PCB Layout Considerations

- Place the 49.9 ohm, 1% resistors, and 0.1µF decoupling capacitor, near the PHYTER TD+/- and RD+/- pins and via directly to the Vdd plane.
- Stubs should be avoided on all signal traces, especially the differential signal pairs. See [Figure 3](#).
- Within the pairs (for example, TD+ and TD-) the trace lengths should be run parallel to each other and matched in length. Matched lengths minimize delay differences, avoiding an increase in common mode noise and increased EMI. See [Figure 3](#).
- Ideally there should be no crossover or via on the signal paths. Vias present impedance discontinuities and should be minimized. Route an entire trace pair on a single layer if possible.

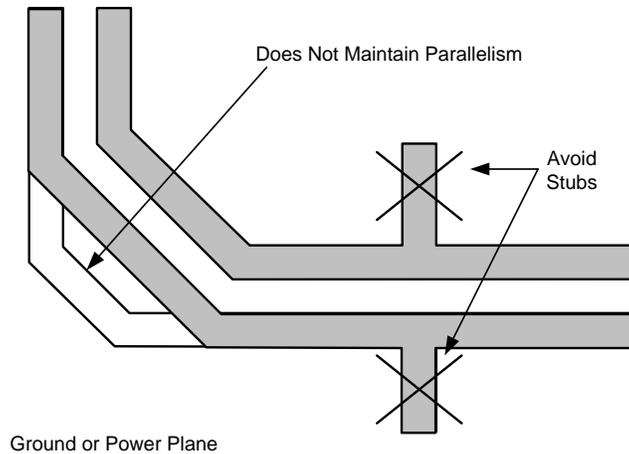


Figure 3. Differential Signal Pair - Stubs

- PCB trace lengths should be kept as short as possible.
- Signal traces should not be run such that they cross a plane split. See [Figure 4](#). A signal crossing a plane split may cause unpredictable return path currents and would likely impact signal quality as well, potentially creating EMI problems.

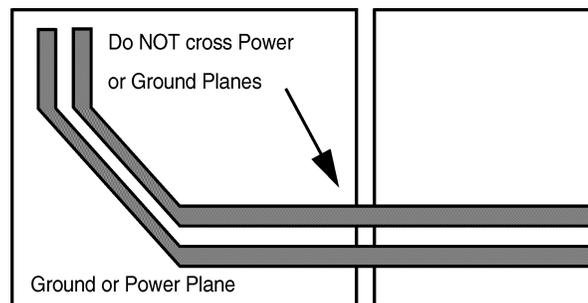


Figure 4. Differential Signal Pair-Plane Crossing

- MDI signal traces should have 50 ohm to ground or 100 ohm differential controlled impedance. Many tools are available online to calculate this.

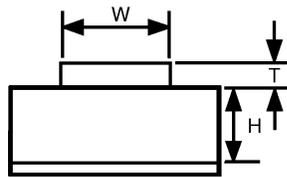
2.2 Calculating Impedance

The following equations can be used to calculate the differential impedance of the board.

For microstrip traces, a solid ground plane is needed under the signal traces. The ground plane helps keep the EMI localized and the trace impedance continuous. Since stripline traces are typically sandwiched between the ground/supply planes, they have the advantage of lower EMI radiation and less noise coupling. The trade off of using strip line is lower propagation speed.

Microstrip Impedance - Single-Ended

$$Z_o = \left(\frac{87}{\sqrt{Er + (1.41)}} \right) \ln \left(5.98 \frac{H}{0.8W + T} \right)$$

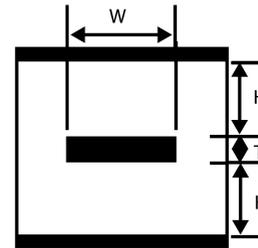


W = Width of the trace H = Height of dielectric above the return plane T = Trace thickness Er = Relative permittivity of the dielectric

Figure 5. Microstrip Impedance - Single-Ended

Stripline Impedance - Single-Ended

$$Z_o = \frac{60}{\sqrt{Er}} \ln \left(1.9 \frac{2H + T}{0.8W + T} \right)$$

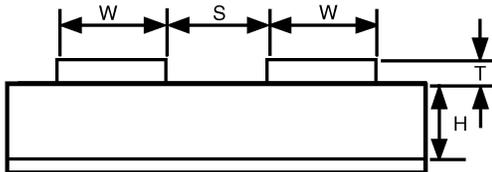


W = Width of the trace H = Height of dielectric above the return plane T = Trace thickness Er = Relative permittivity of the dielectric

Figure 6. Stripline Impedance - Single-Ended

Microstrip Impedance - Differential

$$Z_{diff} = 2Z_o \left(1 - 0.48 \left(e^{\left(-0.96 \frac{S}{H} \right)} \right) \right)$$

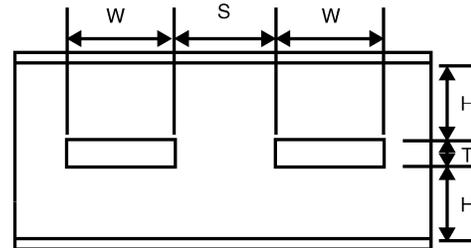


W = Width of the trace H = Height of dielectric above the return plane T = Trace thickness S = Space between traces Er = Relative permittivity of the dielectric

Figure 7. Microstrip Impedance - Differential

Stripline Impedance - Differential

$$Z_o = 2Z_o \left(1 - 0.347 \left(e^{-2.9 \frac{S}{H}} \right) \right)$$



W = Width of the trace H = Height of dielectric above the return plane T = Trace thickness S = space between traces Er = Relative permittivity of the dielectric

Figure 8. Stripline Impedance - Differential

2.3 RJ-45 Connections

The transformer used in the MDI connection provides DC isolation between local circuitry and the network cable. The center tap of the isolated winding has “Bob Smith” termination through a 75 ohm resistor and a 1000 pF cap to chassis ground. The termination capacitor should be rated to a voltage of at least 2kV.

Note: “Bob-Smith termination does not apply for Power Over Ethernet (PoE) applications.

“Bob-Smith” termination is used to reduce noise resulting from common mode current flows, as well as reduce susceptibility to any noise from unused wire pairs on the RJ-45.

2.4 MDI EMI Recommendations

The following recommendations are provided to help improve EMI performance:

- Use a metal shielded RJ-45 connector, and connect the shield to chassis ground.
- Use magnetics with integrated common mode choking devices.
- Do not overlap the circuit and chassis ground planes, keep them isolated. Connect chassis ground and system ground together using two size 1206 zero ohm resistors across the void between the ground planes on either side of the RJ-45. These resistors can be removed or replaced with alternative components (that is, capacitors or EMI beads) during system level certification testing if necessary.

3 Fiber Optic Implementations

Some PHYTER family products include the ability to utilize the MDI interface to connect to fiber optic transceivers. Individual device datasheets describe how to terminate the MDI signals when enabling Fiber Mode in these devices.

Although the termination requirements for fiber mode operation differ from the termination requirements of twisted pair operation, the characteristic impedance of the terminations and the associated signal traces are the same. Therefore, the same MDI signal routing recommendations described in [Section 2.1](#) of this document apply to Fiber enabled systems as well.

4 Power Supply Filtering

The device Vdd supply pins should be bypassed with low impedance 0.1 μF surface mount capacitors. To reduce EMI, the capacitors should be placed as close as possible to the component Vdd supply pins, preferably between the supply pins and the vias connecting to the power plane. In some systems it may be desirable to add 0 ohm resistors in series with supply pins, as the resistor pads provide flexibility if adding EMI beads becomes necessary to meet system level certification testing requirements. (See [Figure 9](#).)

It is recommended the PCB have at least one solid ground plane and one solid Vdd plane to provide a low impedance power source to the component. This also provides a low impedance return path for non-differential digital MII and clock signals.

A 10.0 μF capacitor should also be placed near the PHY component for local bulk bypassing between the Vdd and ground planes.

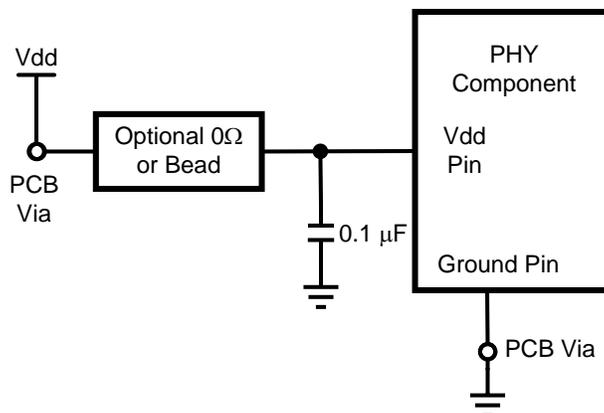


Figure 9. Vdd Bypass Layout

4.1 Power Feedback Supply

Some PHYTER products utilize PCB traces to connect an internal regulator to core supply pins. On these products, the PFBOUT pin should be tied to the PFBIN1 & 2 pins using as much PCB copper as possible. A 10.0 μF tantalum capacitor in parallel with a 0.1 μF cap should be placed close to the PFBOUT pin, and 0.1 μF caps should be placed close to the PFBIN1 and PFBIN2 pins. (See [Figure 10](#))

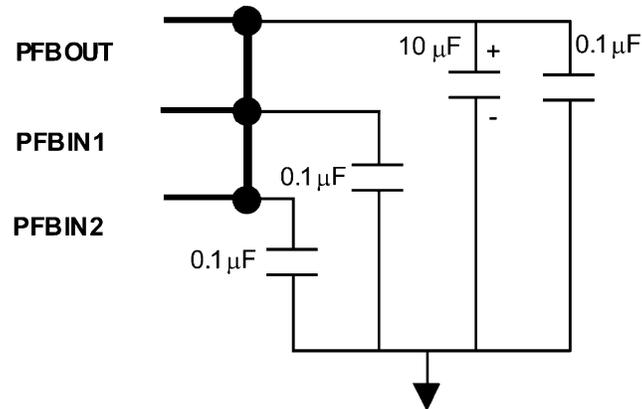


Figure 10. Power Feedback Connection

5 MAC Interface (MII/RMII)

The Media Independent Interface (MII) connects the PHYTER component to the Media Access Controller (MAC). The MAC may in fact be a discrete device, integrated into a microprocessor, CPU or FPGA. On the MII signals, the IEEE specification states the bus should be 68 ohm impedance.

For space critical designs, the PHYTER family of products also support Reduced MII (RMII). For additional information on this mode of operation, refer to the *AN-1405 DP83848 Single 10/100 Mb/s Ethernet Transceiver Reduced Media Independent Interface (RMII) Mode Application Report* ([SNLA076](#)).

5.1 Termination Requirement

To reduce digital signal energy, 50 ohm series termination resistors are recommended for all MII output signals (including RXCLK, TXCLK, and RX Data signals.) Note that DP83849 and DP83640 products provide integrated 50 ohm signal terminations, making external termination resistors unnecessary.

5.2 Recommended Maximum Trace Length

Although RMII and MII are synchronous bus architectures, there are a number of factors limiting signal trace lengths. With a longer trace, the signal becomes more attenuated at the destination and thus more susceptible to noise interference. Longer traces also act as antennas, and if run on the surface layer, can increase EMI radiation. If a long trace is running near and adjacent to a noisy signal, the unwanted signals could be coupled in as cross talk.

It is recommended to keep the signal trace lengths as short as possible. Ideally, keep the traces under 6 inches.

Trace length matching, to within 2.0 inches on the MII or RMII bus is also recommended. Significant differences in the trace lengths can cause data timing issues.

As with any high speed data signal, good design practices dictate that impedance should be maintained and stubs should be avoided throughout the entire data path.

6 Clock Requirements

PHYTER family products support either an external CMOS level oscillator source or a crystal resonator device. The X1 pin is the clock input, requiring either 25 or 50 MHz depending on the MII mode used.

In MII mode (or RMII master mode in some products) either a 25 MHz crystal or 25 MHz oscillator may be used. For all PHYTER family products, the use of standard RMII mode (not RMII master mode) requires the use of a 50 MHz oscillator.

The input clock signal is also buffered and provided as an output signal on some PHYTER family products.

6.1 External Oscillator Clock Source

If an oscillator is used, X1 should be tied to the clock source and X2 should be left floating. No series or load termination is required from the clock source, but may prove beneficial in some circumstances.

For EMI purposes, it may be beneficial to include series termination to limit the energy sourced from the oscillator. If series termination is used, the termination resistor should be placed as close to the oscillator output as possible on the PCB.

For longer traces, series termination coupled with matched parallel termination to ground and matched trace impedance may prove beneficial as well. If a parallel termination resistor is used, it should be placed as closely as possible to the X1 pin.

Connections for using an oscillator are shown in [Figure 11](#).

Specifications for CMOS oscillators are listed in [Section 10.1](#).

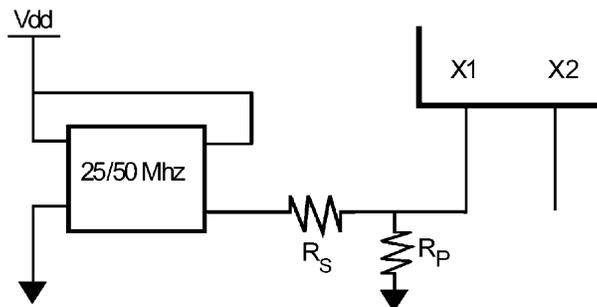


Figure 11. Oscillator Circuit

6.2 Crystal Clock Source

For MII mode (or RMII master mode on the DP83640), the recommended crystal to use is a 25 MHz, parallel, 20 pF load crystal resonator. [Figure 12](#) shows a typical circuit for a crystal resonator. The load capacitor values will vary with the crystal vendors; check with the vendor for load recommendations.

Approximate load capacitor values can be calculated by:

$$2 \times \text{Crystal load spec} - 7 \text{ pF} = C_L \quad (1)$$

The oscillator circuit is designed to drive a parallel resonance AT cut crystal with a minimum drive level of 100 mW and a maximum of 500 mW. If a crystal is specified for a lower drive level, a current limiting resistor should be placed in series between X2 and the crystal.

As a starting point for evaluating an oscillator circuit, if the requirements for the crystal are not known, C_{L1} and C_{L2} should be set at 33 pF, and R_1 should be set at 0 Ohms.

Specifications for the crystal are listed in [Section 10.1](#).

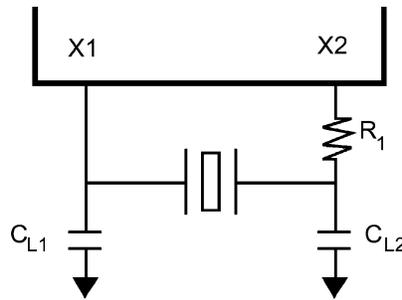


Figure 12. Crystal Oscillator Circuit

7 LED and non-LED Strap Pins

PHYTER products support both conventional configuration strap input/output pins and multi-purpose Light Emitting Diode (LED) I/O pins. The LED pins can display the status of Link, Speed, Activity, or the presence of Collisions.

Many conventional strap input/output pins have high impedance (10k to 20k) default strap resistors present internal to the device. In order to overdrive these internal strap resistors, it is recommended that 2.2k resistors be used for selecting non-default strap options.

Additionally, even though the internal strap resistors are adequate for configuring the device in most applications, in some applications with noisy environments it is recommended that additional external 2.2k straps be used to select default options as well.

With regard to multi-purpose LED I/O pins, in order to achieve dual input/output functionality, the active state of each LED output driver is dependent on the input logic level sampled during power-up/reset. For example, if a multifunction LED pin is resistively pulled low, then the corresponding output will be configured as active high. Conversely, if an input is resistively pulled high, then the corresponding output will be configured as active low.

Figure 13 illustrates examples of both conventional and multi-purpose LED pin strap configurations.

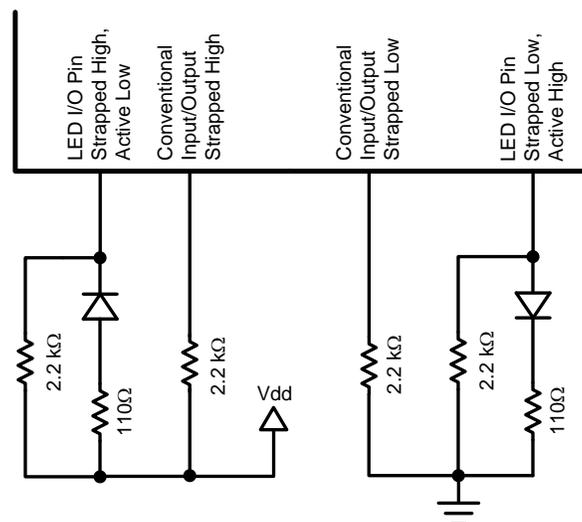


Figure 13. AN Strapping and LED Loading Example

8 PCB Layer Stacking

To meet signal integrity and performance requirements, at minimum a four layer PCB is recommended for implementing PHYTER components in end user systems. The following layer stack-ups are recommended for four, six, and eight-layer boards, although other options are possible.

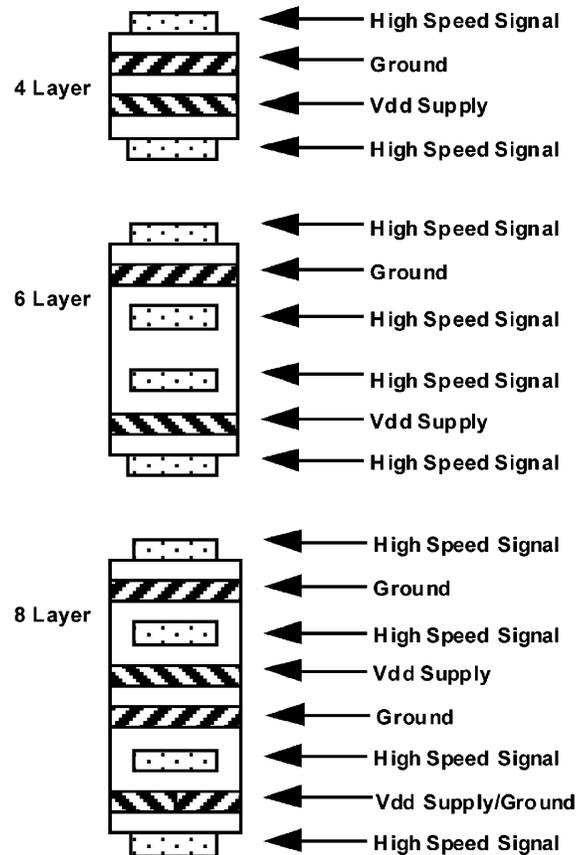


Figure 14. PCB Stripline Layer Stacking

Within a PCB it may be desirable to run traces using different methods, microstrip vs. stripline, depending on the location of the signal on the PCB. For example, it may be desirable to change layer stacking where an isolated chassis ground plane is used. [Figure 15](#) illustrates alternative PCB stacking options.

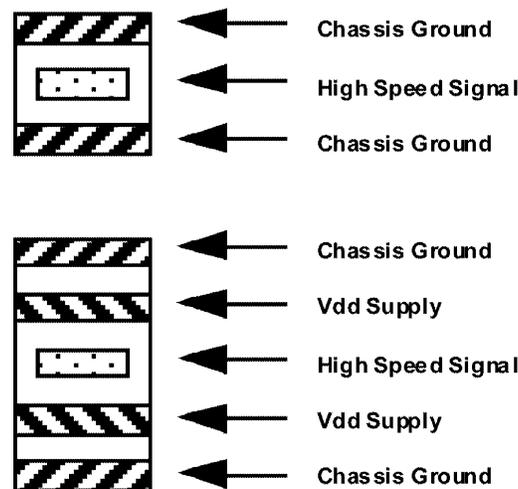


Figure 15. Alternative PCB Stripline Layer Stacking

9 Unused Pins/Reserved Pins

The PHYTER family of products provide internal pull-ups or pull-downs on most pins. The datasheets for the specific products detail which pins have internal pull-ups or pull-downs, and which pins require external pull resistors.

Even though a device may have internal pull-up or pull-down resistors, a good practice is to terminate unused CMOS inputs, rather than allowing them to float. Floating inputs could result in unstable conditions.

In theory, CMOS inputs can be tied directly to Vdd or ground, minimizing component count and board area. However, its considered a safer practice to pull an unused input pin high or low with a pull-up or pull-down resistor. It is also possible to group together adjacent unused input pins, and as a group pull them up or down using a single resistor.

10 Component Selection

Within a design, selection of certain components is critical. This is due to the device being designed to specific criteria of critical parameters. These components include:

- Clock source - oscillator or crystal
- Magnetics

10.1 Oscillator or Crystal

The parametric specifications for utilizing an external oscillator are shown in [Table 1](#).

The commonly used crystal is “AT cut” and fundamental frequency. This is the recommended type for PHYTER components since AT cut exhibits the most frequency stability over a wide temperature range. The requirements for 25 MHz crystals are listed [Table 2](#).

In the case where multiple clock sources are needed, a high speed PLL clock distribution driver is recommended. The drivers may be obtained from vendors such as Texas Instruments, Pericom, and Integrated Device Technology. Please consult vendor for specifics.

Contact oscillator manufactures for latest information on part numbers and product specifications. All oscillators and circuits should be thoroughly tested and validated before use in production.

Table 1. 25 MHz Crystal Oscillator Requirements

Parameter	Min	Typ	Max	Units	Condition
Frequency	-	25 / 50	-	MHz	
Frequency Stability	-	-	± 50	ppm	0°C to 70°C, 1 year aging, load change
Rise/Fall Time	-	-	6	ns	20 - 80%
Jitter (short term)	-	-	25	ps	Cycle-to-cycle, driving 10 pF load
Jitter (long term)	-	-	200	ps	Accumulative over 10 μs
Load Capacitance	15	-	-	pF	
Symmetry	40	-	60	%	
Logic 0	-	-	10% VDD	V	VDD = 3.3 V nominal
Logic 1	90% VDD	-	-	V	VDD = 3.3 V nominal

Table 2. 25 MHz Crystal Requirements

Parameter	Min	Typ	Max	Units	Condition
Frequency	-	25	-	MHz	-
Frequency Tolerance	-	-	± 50	ppm	0°C to 70°C
Frequency Stability	-	-	± 50	ppm	1 year aging
Load Capacitance C _L	15	-	40	pF	Total C _L including C1 and C2

Table 3. Recommended Crystal Oscillators

Manufacturer	Part Number
Vectron International	25 MHz 7.5 x 5 mm Crystal Oscillator VCC1-B2B-25M000
Raltron Electronics Corporation	25 MHz 7.5 x 5 mm Crystal Oscillator C04305L-25.000MHz
CTS Valpey Corporation	

10.2 Magnetics

The magnetics have a large impact on the PHY performance as well. While several components are listed below, others may be compatible following the requirements listed in [Table 4](#). It is recommended that the magnetics include both an isolation transformer and an integrated common mode choke to reduce EMI.

When doing the layout, do not run signals under the magnetics. This could cause unwanted noise crosstalk. Likewise void the planes under discrete magnetics, this will help prevent common mode noise coupling.

To save board space and reduce component count, an RJ-45 with integrated magnetics may be used.

Current recommended magnetics are listed in [Table 5](#). Contact magnetics manufactures for latest part numbers and product specifications. All magnetics should be thoroughly tested and validated before using them in production. Other magnetics with comparable characteristics should operate equally well. For a more complete list, visit the PHYTER web page at: www.ti.com.

Table 4. Magnetics Requirements

Parameter	Typ	Units	Condition
Turn Ratio	1:1	-	± 2%
Insertion Loss	-1	dB	1 - 100 MHz
Return Loss	-16	dB	1 - 30 MHz
	- 12	dB	30 - 60 MHz
	- 10	dB	60 - 80 MHz
Differential to Common Rejection Ration	- 30	dB	1 - 50 MHz
	- 20	dB	50 - 150 MHz
Crosstalk	- 35	dB	30 MHz
	- 30	dB	60 MHz
Isolation	1,500	Vrms	HPOT

Table 5. Recommended Magnetics

Manufacturer	Part Number	
Bel Fuse, Inc.	S558-5999-U7	Typical Application
	SI-60062-F	Integrated
Pulse Electronics	H1102	Typical Applications
	H2019	POE Applications
	J0011D21B	Integrated

11 Reset Operation

PHYTER products include an internal power-on reset (POR) function and does not need to be explicitly reset after power up, for normal operation. If required during normal operation, the device can be reset by a hardware or a software reset.

11.1 Hardware Reset

A hardware reset is accomplished by applying a low pulse (TTL level), with a duration of at least 1 ms, to the RESET_N. This will reset the device such that all registers will be re-initialized to default values and the hardware configuration values will be re-latched into the device (similar to the power-up/reset operation).

11.2 Software Reset

A software reset is accomplished by setting the reset bit (bit 15) of the Basic Mode Control Register (BMCR). The period of time from setting the reset bit, to the time when software reset has concluded is approximately 1 ms.

The software reset will reset the device such that all registers will be reset to default values and the hardware configuration values will be maintained. Software driver code must wait 3 ms following a software reset before allowing further serial MII (MDIO/MDC) communications with the device.

12 Other Applicable Documents

The following documents should be used in conjunction with this document, to assist in designing with PHYTER products:

- *DP83848C PHYTER Comm Temp Single Port 10/100Mb/s Ethernet Phy Layer Transceiver* ([SNOSAT2](#))
- *DP83848I Ind Temp Single Port 10/100 Mb/s Ethernet Phy Layer Transceiver* ([SNLS207](#))
- *DP83848YB Extreme Temp Single Port 10/100 Mb/s Ethernet Phy Layer Transceiver* ([SNLS208](#))
- *DP83848M PHYTER Mini - Commercial Temperature Single 10/100 Ethernet Transceiver* ([SNLS227](#))
- *DP83848T PHYTER Mini - Industrial Temp Single 10/100 Ethernet Transceiver* ([SNLS228](#))
- *DP83848VYB PHYTER - Extended Temperature Single Port 10/100 Mb/s Ethernet Physical Layer Xceiver* ([SNLS266](#))
- *DP83848J PHYTER Mini LS Commercial Temperature Single Port 10/100 Mb/s Ethernet Transceiver* ([SNLS250](#))
- *DP83848K PHYTER Mini LS Industrial Temperature Single Port 10/100 Ethernet Transceiver* ([SNLS251](#))
- *DP83848C/I/YB Schematic* ([SNLR019](#))
- *DP83848C/I/YB Bill of Materials* ([SNLR020](#))
- *DP83848M/T/H Schematic* ([SNLR015](#))
- *DP83848M/T/H Bill of Materials* ([SNLR016](#))
- *DP83848J/K Schematic* ([SNLR011](#))
- *DP83848J/K Bill of Materials* ([SNLR012](#))
- *DP83849C PHYTER DUAL Commercial Temperature Dual Port 10/100 Mb/s Ethernet Physical Layer* ([SNOSAX0](#))
- *DP83849I PHYTER DUAL Industrial Temperature with Flexible Port Switching Dual Port* ([SNOSAX1](#))
- *DP83849ID PHYTER DUAL Industrial Temperature with Fiber Support (FX), Dual Port 10/100 Mb/s Ethernet PHY Xceiver* ([SNOSAX2](#))
- *DP83849IF PHYTER DUAL Industrial Temperature with Fiber Support (FX) and FI* ([SNOSAX8](#))
- *DP83640 Precision PHYTER - IEEE® 1588 Precision Time Protocol Transceiver* ([SNOSAY8](#))
- *AN-1519 DP83848 PHYTER® Transformerless Ethernet Operation Application Report* ([SNLA088](#))
- IEEE 802.3 and 802.3u specifications (For 10/100 Mb/s operation)
- [PCB Trace Impedance Calculator](#)
- [Differential Impedance](#)

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Applications Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community

e2e.ti.com